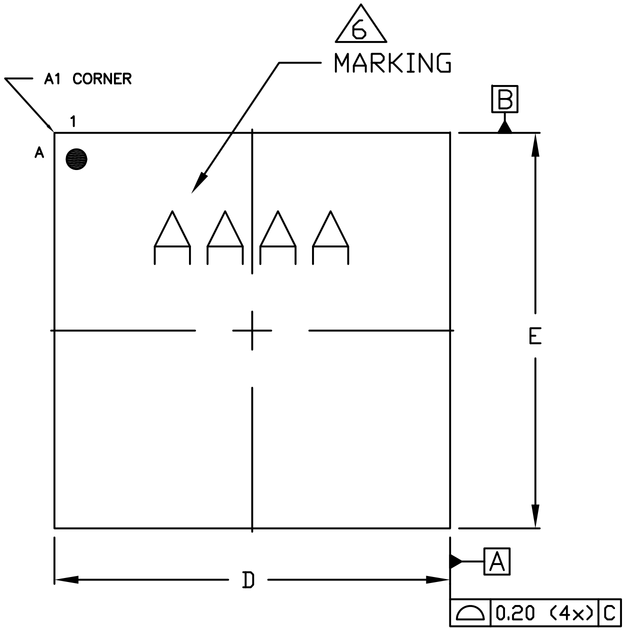
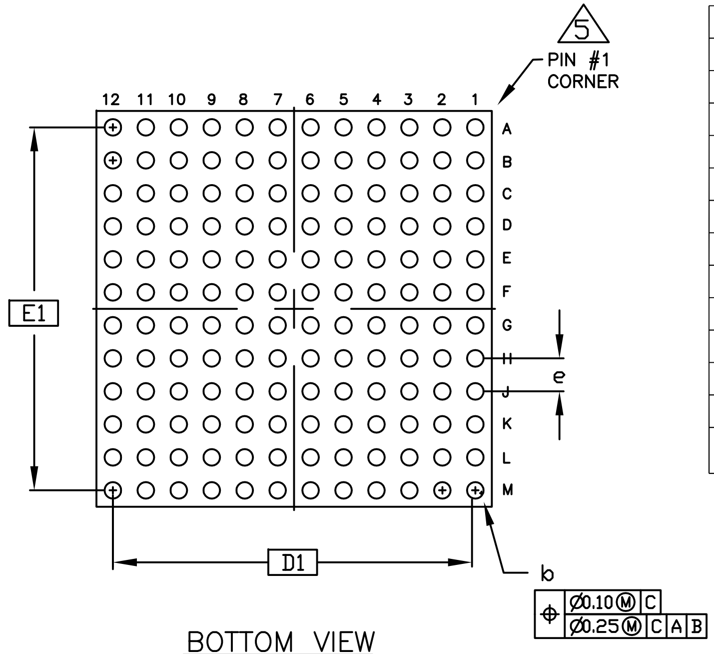
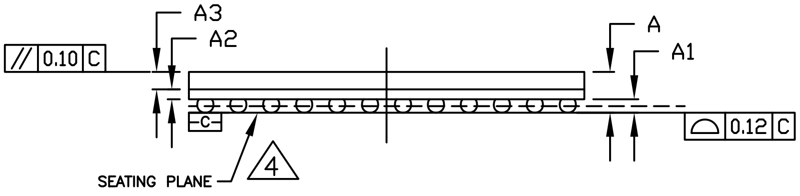


TOP VIEW



BOTTOM VIEW

DIMENSIONS			
REF.	MIN.	NOM.	MAX.
A	1.14	1.24	1.34
A1	0.36	0.41	0.46
A2	0.30 REF		
A3	0.53 REF		
D	11.80	12.00	12.20
D1	11.00 BSC		
E	11.80	12.00	12.20
E1	11.00 BSC		
b	0.54		
e	1.00 BSC		
N	144		
PKG. CODE: X14422FH#1			



SIDE VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.
3. THE BASIC SOLDER BALL GRID PITCH IS 1.00MM AND BALL DIA IS 0.50MM.
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. A1 BALL PAD CORNER I.D.
6. MARKING SHOWN IS FOR PKG. ORIENTATION ONLY.
7. ALL DIMENSIONS APPLY TO ROHS EXEMPT (#) PKG. CODE ONLY.
8. THIS IS A CUSTOM PACKAGE.

-DRAWING NOT TO SCALE-

TITLE:
PACKAGE OUTLINE, 144 BALLS
FLIP CHIP CSP, 12x12x1.2mm

APPROVAL	DOCUMENT CONTROL NO.	REV.	
	21-0578	A	1/1